

REMARKS

The undersigned, a pro-se applicant, respectfully requests that if the Examiner finds patentable subject matter disclosed in this application, but feels that Applicant's present claim is not entirely suitable, the Examiner draft one or more allowable claims for applicant.

This case has been carefully reviewed and analyzed in view of the Official Action dated July 31, 2002.

The Examiner has objected to Figures 1a, 1b and 2. A red-lined photocopy of the drawings for FIGS. 1a, 1b and 2 are submitted for the Examiner's approval.

Further, the Examiner has rejected claim 5 under 35 U.S.C. 112, first paragraph, as containing subject matter which was not disclosed in the specification in such a way as to enable one skilled in the art to which it pertains, or with which it is most nearly connected, to make and/or use the invention. Claim 5 has been canceled and replaced with new claim 6 in order to avoid this rejection. However, if the new claim still does not comply with the requirement, an Examiner's amendment is earnestly solicited.

Moreover, the Examiner has rejected claim 5 under 35 U.S.C. 103(a) as being unpatentable over US 6,288,904, granted to Houdeau et al in view of EP 0463871A2, granted to Jarvis. Nevertheless, it is respectfully requested that this rejection be withdrawn in light of the following reasons.

Houdeau et al, the first reference cited by the Examiner, discloses a chip module for implantation in a smart card body. However, the Houdeau et al reference is designed for implantation in a smart card body, whereas the present invention is directed to an ultra-thin film package. Furthermore, the electrode of the metal pad protruded from the back side of the polymeric film die carrier or PI die carrier according to the present invention can greatly improve the connection with the

printed circuit board by soldering. In addition, this reference fails to disclose an ultra-thin film package, wherein polymeric film die carrier or polyimide (PI) die carrier is employed, and the leg position for die bonding is made into a recess shape to lower the thickness after bonding, and polymeric film die carrier or PI die carrier is made into a thin film shape by a fabrication technique, and the I/O leg position is made into a recess shape and the die is glued to the polymeric film die carrier or PI die carrier and then changed with a package material, and by means of a dicing step, a single package granule containing dies is cut, wherein an end of a wire is mounted with a metal pad within the leg position which is recessed on the polymeric die film carrier or PI die carrier, and the electrode of the metal pad is protruded from the back face of the polymeric film die carrier, or PI die carrier, a metal plate is provided at the polymeric film die carrier, or PI die carrier, corresponding to the back face of the die position, the electrical bonding of the die with polymeric film die carrier or PI die carrier is a die bonding method such that the I/O bump of the die and the metal pad on the leg position of the polymeric film die carrier or PI die carrier are bonded. Hence, this reference can be clearly distinguished from the present invention both in purpose and structure.

Jarvis, the second reference cited by the Examiner, discloses an integrated circuit token fitted within the lower portion with an aluminum foil for heat dissipation, while the present invention simply comprises a metal plate which is externally mounted on the bottom. Similarly, this reference does not teach or suggest an ultra-thin film package, wherein polymeric film die carrier or polyimide (PI) die carrier is employed, and the leg position for die bonding is made into a recess shape to lower the thickness after bonding, and polymeric film die carrier or PI die carrier is made into a thin film shape by a fabrication technique, and the I/O leg position is made into a recess shape and the die is glued to the polymeric film die carrier or PI

die carrier and then changed with a package material, and by means of a dicing step, a single package granule containing dies is cut, wherein an end of a wire is mounted with a metal pad within the leg position which is recessed on the polymeric die film carrier or PI die carrier, and the electrode of the metal pad is protruded from the back face of the polymeric film die carrier, or PI die carrier, a metal plate is provided at the polymeric film die carrier, or PI die carrier, corresponding to the back face of the die position, the electrical bonding of the die with polymeric film die carrier or PI die carrier is a die bonding method such that the I/O bump of the die and the metal pad on the leg position of the polymeric film die carrier or PI die carrier are bonded. Consequently, this reference is in no way similar to the present invention.

Accordingly, even if the cited references are combined together, the ultra thin film package as claimed would not be found. Moreover, the combined disclosure of the cited references fails to teach each and every element of the claimed invention and so the subject matter sought to be patented as a whole would not have been obvious to one of ordinary skill in the art.

It is now believed that the subject Patent Application has been placed in condition of allowance, and such action is respectfully requested.

Respectfully submitted,

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President

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